

**Amendments to the Specification:**

Please replace the paragraph beginning on page 49, line 19, with the following rewritten paragraph:

According to a second method, in manufacturing the electronic device 10, the electronic component 13 is fabricated in expectation of a change in the characteristics of the electronic component 13 between before and after the adhering step, so as to attain desired characteristics of the electronic component 13 after the adhering step. For example, this method is accomplished as follows. First, the processing conditions to be employed in the adhering step are determined such that the amount of change in the center frequency between before and after the adhering step will fall within a predetermined amount. Then, in expectation of the change in the center frequency between before and after the adhering step, the electronic component 13 is fabricated so as to obtain a desired center frequency after the adhering step. This means that the electronic component 13 is fabricated such that the center frequency shifts from the desired frequency by the predetermined amount. The adhering step is then carried out under the predetermined conditions, thereby attaining a center frequency closer to the desired frequency.